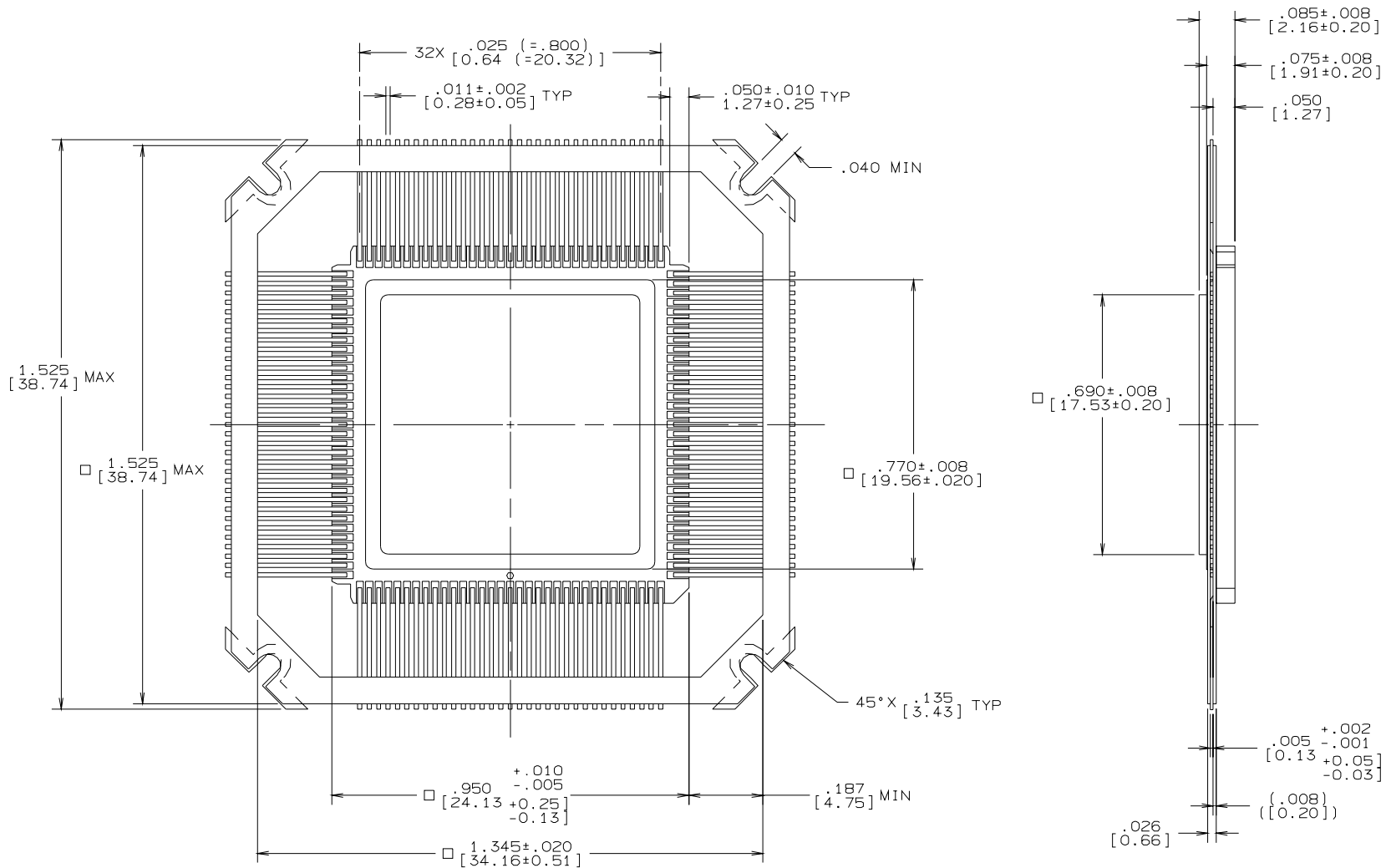


R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	07569	12/05/89	DEG/AP
B	REDRAW, REVISE TIE BAR CORNERS.	08359	03/04/91	PG/AP
C	1.525 [38.74] MAX WAS 1.495±.010 [37.72±0.25]; 1.345±.020 [34.16±0.51] WAS 1.345±.010 [34.16±0.25]	11775	07/28/1997	MS/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. PLATING SHALL BE 60 MICROINCHES / 1.52 MICROMETERS GOLD OVER
50-350 MICROINCHES / 1.27-8.89 MICROMETERS NICKEL.

APPROVALS	DATE	 2900 Semiconductor dr, Santa Clara, CA 95052-8090	
DRAWN P. GIFFORD	03/04/91		
DFTG. CHK.		LEADED CHIP CARRIER, 132 LD, NON-CONDUCTIVE TIE BAR	
ENGR. CHK.			
 PROJECTION INCH [MM]		SCALE 5X	SIZE C
		DRAWING NUMBER (SC)MKT-EL132C	REV C
DO NOT SCALE DRAWING		SHEET 1 OF 1	